



GAU 1752

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Kie Y. Ahn et al.

Title: SELECTIVE ELECTROLESS-PLATED COPPER METALLIZATION

Docket No.: 303.672US1

Serial No.: 09/483,881

Filed: January 18, 2000

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Examiner: Unknown

Group Art Unit: Unknown

Commissioner for Patents  
Washington, D.C. 20231

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We are transmitting herewith the following attached items (as indicated with an "X"):

- X A return postcard.
- X An Information Disclosure Statement (1 pgs.), Form 1449 (6 pgs.), and copies of 62 cited references.
- X A Communication Concerning Co-Pending Applications (1 pg.).

Please consider this a **PETITION FOR EXTENSION OF TIME** for sufficient number of months to enter these papers and please charge any additional required fees or credit overpayment to Deposit Account No. 19-0743.

**CERTIFICATE UNDER 37 CFR 1.8:** The undersigned hereby certifies that this Transmittal Letter and the paper, as described above, are being deposited in the United States Postal Service, as first class mail, in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231, on this 23 day of June, 2000.

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(GENERAL)